

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

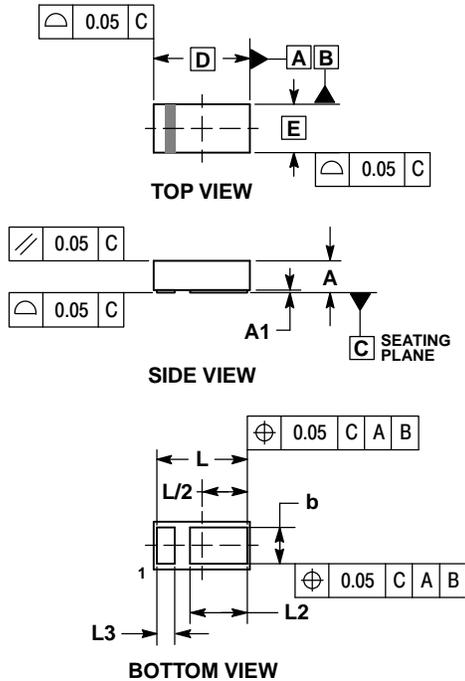
ON Semiconductor®



SCALE 8:1

DSN2, 1.6x0.8, 0.9P, (0603)
CASE 152AB
ISSUE C

DATE 30 APR 2017

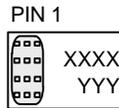


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

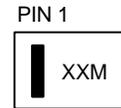
DIM	MILLIMETERS	
	MIN	MAX
A	0.25	0.31
A1	---	0.05
b	0.55	0.65
D	1.60 BSC	
E	0.80 BSC	
L	1.45	1.55
L2	0.90	1.00
L3	0.25	0.35

GENERIC MARKING DIAGRAM1*



XXXX = Specific Device Code
YYY = Year Code

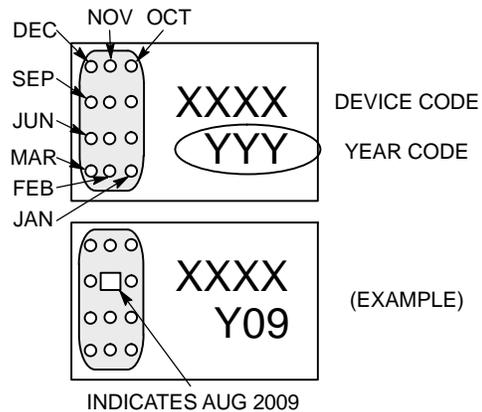
GENERIC MARKING DIAGRAM2*



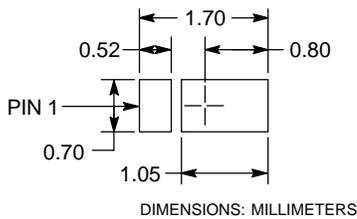
XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

CATHODE BAND MONTH CODING



MOUNTING FOOTPRINT*



See Application Note AND8464/D for more mounting details

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	DSN2, 1.6X0.8, 0.9P, (0603)	PAGE 1 OF 2

